

METHOD AND APPARATUS FOR DELIVERING  
POWER TO HIGH PERFORMANCE ELECTRONIC ASSEMBLIES

ABSTRACT OF THE DISCLOSURE

5 A method, apparatus, and article of manufacture for providing power from a first  
circuit board having a first circuit board first conductive surface and a first circuit board  
second conductive surface to a second circuit board having a second circuit board first  
conductive surface and a second circuit board second conductive surface is described.  
The apparatus comprises a first conductive member, including a first end having a first  
10 conductive member surface electrically coupleable to the first circuit board first  
conductive surface and a second end distal from the first end having a first conductive  
member second surface electrically coupleable to the second circuit board first surface.  
The apparatus also comprises a second conductive member, having a second conductive  
member first surface electrically coupleable to the first circuit board second surface and a  
15 second conductive member second surface distal from the second conductive member  
first surface electrically coupleable to the second circuit board second conductive surface.

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